



**PRODUCT CHANGE NOTICE**

**PCN-2691-REV1**

<b>Notification Date:</b>	<b>Implementation Date:</b>	<b>Product Family:</b>	<b>Change Type:</b>	<b>PCN #:</b>
16 August, 2024	14 November, 2024	Discrete Semiconductor	Additional Wafer Source, Wafer Diameter, Metallization System, Wire Bond Material	<b>2691</b>
<b>TITLE</b>				
Additional Wafer Sources and Transfer of Wafer Manufacturing Site for Select Discrete Products				
<b>DESCRIPTION OF CHANGE</b>				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified the following wafer source changes for select discrete products listed below.</p> <ul style="list-style-type: none"><li>• Diodes internal wafer fabrication source (JKFAB) in Hsinchu, Taiwan as additional wafer source, and Diodes internal assembly and test site (SAT) located in Shanghai, China and Diodes internal assembly and test site (CAT) located in Chengdu, China for processing wafer back metal (BM).</li><li>• Diodes internal wafer fabrication source (SFAB2) in Shanghai, China as additional wafer source with wafer top metal (TM) and back metal (BM) being processed at Diodes internal CAT site. Wafer top metal will be changed from TiNiAg to NiAu at CAT.</li><li>• Diodes internal wafer fabrication source WX1 in WuXi, China as new wafer source. Affected products will be transferred from Diodes internal wafer fabrication source SSEC in Shanghai, China, which is planned to be closed by 31 August 2024.</li><li>• Diodes external wafer fabrication source Yea Shin Technology Co., Ltd. in Keelung, Taiwan, manufacture of 6-inch diameter wafers with a standardized metal system (back metal composition) in addition to the currently qualified 4-inch diameter wafers.</li><li>• Diodes external wafer fabrication source Phenittec Semiconductor Corporation (PTS) 1<sup>st</sup> FAB in Okayama, Japan as additional wafer source using Au bond wire at Diodes internal SAT site.</li></ul> <p>Full electrical characterization and reliability testing have been completed on representative part numbers to ensure there is no change to product reliability, device functionality or electrical specifications in the datasheet.</p> <p>There will be no change to the Form, Fit, or Function of affected products.</p>				
<b>IMPACT</b>				
No change in datasheet parameters				
<b>PRODUCTS AFFECTED</b>				
Table 1 – Affected part list to add JKFAB as additional wafer source, and add SAT and CAT for BM Table 2 – Affected part list to add SFAB2 as additional wafer source, and add CAT for TM and BM Table 3 – Affected part list to transfer to WX1 FAB as new wafer source Table 4 – Affected part list to add Yea Shin 6-inch diameter wafer as additional wafer source Table 5 – Affected part list to add PTS 1st FAB as additional wafer source using Au bond wire at SAT				



WEB LINKS	
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DISCLAIMER	
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days from the notification date of this PCN, all changes described in this announcement are considered approved.	

Table 1 - Affected part list to add JK FAB as additional wafer source, and add SAT and CAT for BM					
BC53-16PA-7	BCX5216TA	D3Z30BF-7	DDZ9713T-7	FZT953TA	MMBZ5258BW-7-F
BC807-16-7-F	BCX5216TC	D3Z33BF-7	DDZ9714T-7	FZT955TA	MMBZ5259BS-7-F
BC807-16W-7	BCX52TA	D3Z36BF-7	DDZ9715T-7	MJD32C-13	MMBZ5259BT-7-F
BC807-25-7-F	BCX5316-13R	DDZ28-7	DDZ9716T-7	MMBTA55-7-F	MMBZ5259BTS-7-F
BC807-25W-7	BCX5316TA	DDZ30ASF-7	DDZ9717T-7	MMBTA56-7-F	MMBZ5259BW-7-F
BC807-40-13-F	BCX5316TC	DDZ30BSF-7	DDZX36-7	MMBZ5255BS-7-F	MMDT4413-7-F
BC807-40-7-F	BCX53TA	DDZ30CSF-7	DMB2227A-7	MMBZ5255BT-7-F	MMSTA55-7-F
BC807-40W-7	BCX53TC	DDZ30DS-7	DPLS350E-13	MMBZ5255BTS-7-F	MMSTA56-7-F
BCM846BS-7	BZT52C43-7-F-79	DDZ30DSF-7	DPLS350Y-13	MMBZ5255BW-7-F	MMSZ5255B-7-F
BCM847BS-7	BZX84C30S-7-F	DDZ33ASF-7	DPLS350YTC	MMBZ5256BS-7-F	MMSZ5255BS-7-F
BCP5116TA	BZX84C30T-7-F	DDZ33BSF-7	DT955-7	MMBZ5256BT-7-F	MMSZ5256B-13-F
BCP5116TC	BZX84C30W-7-F	DDZ33CSF-7	DXT2222A-13	MMBZ5256BTS-7-F	MMSZ5256B-7-F
BCP51TA	BZX84C33S-7-F	DDZ33DSF-7	DXT2907A-13	MMBZ5256BW-7-F	MMSZ5256BS-7-F
BCP5216TA	BZX84C33T-7-F	DDZ34-7	DXT3906-13	MMBZ5257BS-7-F	MMSZ5257B-7-F
BCP52TA	BZX84C33W-7-F	DDZ36ASF-7	DXTP06080BFG-7	MMBZ5257BT-7-F	MMSZ5257BS-7-F
BCP5316TA	BZX84C36S-7-F	DDZ36BSF-7	DXTP07100BFG-7	MMBZ5257BTS-7-F	MMSZ5258B-7-F
BCP5316TC	BZX84C36T-7-F	DDZ36CSF-7	DZDH0401DW-7	MMBZ5257BW-7-F	MMSZ5258BS-7-F
BCP53TA	BZX84C36W-7-F	DDZ36DSF-7	FZT753TA	MMBZ5258BS-7-F	MMSZ5259B-7-F
BCX5116TA	BZX84C39S-7-F	DDZ39ASF-7	FZT753TC	MMBZ5258BT-7-F	MMSZ5259BS-7-F
BCX5116TC	BZX84C39T-7-F	DDZ39BSF-7	FZT792ATA	MMBZ5258BTS-7-F	ZXT953KTC
BCX51TA	BZX84C39W-7-F	DDZ39CSF-7			

Table 2 - Affected part list to add SFAB2 as additional wafer source, and add CAT for TM and BM					
SBR140S1F-7	SBR1U150SA-13	SBR2A150SA-13	SBR2U150SA-13	SBR3150SB-13	

**Table 3 - Affected part list to transfer to WX1 FAB as new wafer source**

1N4933G-T	KBP4T10	RABS20M	RS1J-13-F	RS2G-13-F	RS3G-13-F
1N4934G-T	MRS30M	RABS20M-13	RS1JB-13-F	RS2GA-13-F	RS3GB_HF
1N4935G_HF	MRS30M-13	RH02-T	RS1K-13-F	RS2J_HF	RS3GB-13-F
1N4935G-T	MSB30TM	RH04-T	RS1KB-13-F	RS2J-13-F	RS3J_HF
1N4937G-T	PR1004G_HF	RH06-T	RS1KP1M-7	RS2JA-13-F	RS3J-13-F
ABS10TM	PR1004G_HF-A52	RKBP410	RS1M_HF	RS2K-13-F	RS3JB-13-F
ABS20T1M	PR1005G_HF	RKBP410-LS	RS1M-13-F	RS2M_HF	RS3K_HF
ABS20TM	PR1005G-T	RS1A-13-F	RS1MB-13-F	RS2M-13-F	RS3K-13-F
FRS1JE	PR1006G_HF	RS1AB-13-F	RS1MEWF-7	RS2MA_HF	RS3KB-13-F
FRS1JE-7	PR1006G-T	RS1B-13-F	RS1MSWFM-7	RS2MA-13-F	RS3M-13-F
FRS1MD_HF	PR1007G_HF	RS1BB-13-F	RS2A-13-F	RS3A-13-F	RS3MB_HF
FRS1ME	PR1007G_HF-A52	RS1D-13-F	RS2AA-13-F	RS3AB-13-F	RS3MB-13-F
FRS1ME-13	PR1007G-T	RS1DB-13-F	RS2B-13-F	RS3B-13-F	RS5KP5M-13
FRS1ME-7	PR1505G_HF	RS1G_HF	RS2BA-13-F	RS3BB-13-F	RTT410
FRS3MB_HF	PR2006G_HF-A52	RS1G-13-F	RS2D-13-F	RS3D-13-F	RTT410-13
FS1MED-7	PR2007G_HF	RS1GB-13-F	RS2DA-13-F	RS3DB-13-F	TT4TM
FS2MED_HF	PR3007G_HF	RS1J_HF	RS2G_HF	RS3G_HF	TT8T08-13
FS2MED-7					

**Table 4 - Affected part list to add Yea Shin 6-inch diameter wafer as additional wafer source**

DTH8E06D	FES1JD_HF	LTTH806SDFW	MUR460D	SF20JG_HF	STPR1030
DTH8E06FP	LTTH806EFW	LTTH806SDFW_NC	MUR460D_FR	SF30GG_HF	STPR2020
DTH8R06D	LTTH806RDW	LTTH806SDW_NC	MUR460-T	SF30JG_HF	STPR2030
DTH8R06D1-13	LTTH806RFW	MUR120-T	SF10DG_HF	SF40DG_HF	STPS1020
DTH8R06FP	LTTH806RFW_NC	MUR140-T	SF10GG_HF-A52	SF50JG_HF	STPS1620
DTH8S06D	LTTH806RW	MUR460_E	SF20DG_HF	STPF1030	STPS2020
DTH8S06FP	LTTH806SDF	MUR460-A52	SF20GG_HF	STPR1020	

**Table 5 - Affected part list to add PTS 1st FAB as additional wafer source using Au bond wire at SAT**

BZT52HC10WF-7	BZT52HC18WF-7	BZT52HC2V4WF-7	BZT52HC39WF-7	BZT52HC43WF-7	BZT52HC6V2WF-7
BZT52HC11WF-7	BZT52HC20WF-7	BZT52HC2V7WF-7	BZT52HC3V0WF-7	BZT52HC4V3WF-7	BZT52HC6V8WF-7
BZT52HC12WF-7	BZT52HC22WF-7	BZT52HC30WF-7	BZT52HC3V3WF-7	BZT52HC4V7WF-7	BZT52HC7V5WF-7
BZT52HC13WF-7	BZT52HC24WF-7	BZT52HC33WF-7	BZT52HC3V6WF-7	BZT52HC5V1WF-7	BZT52HC8V2WF-7
BZT52HC15WF-7	BZT52HC27WF-7	BZT52HC36WF-7	BZT52HC3V9WF-7	BZT52HC5V6WF-7	BZT52HC9V1WF-7
BZT52HC16WF-7					

Note: Change wire bond material from Cu to Au at SAT for the parts listed in Table 5